

Special Issue

Physics-Driven AI Applications in Additive Manufacturing and Welding

Message from the Guest Editors

This Special Issue aims to bring together contributions spanning the full spectrum from fundamental thermal-fluid analysis to emerging intelligent data-driven modeling and monitoring approaches in welding and additive manufacturing. We particularly encourage submissions that leverage machine learning and hybrid physics-data methods to address long-standing challenges in process monitoring, modeling and optimisation.

Guest Editors

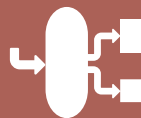
Dr. Van Anh Nguyen

Dr. Yue Cao

Dr. Giulio Mattera

Deadline for manuscript submissions

31 January 2027



Processes

an Open Access Journal
by MDPI

Impact Factor 3.4
CiteScore 5.7

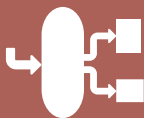


mdpi.com/si/283751

Processes
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
processes@mdpi.com

[mdpi.com/journal/
processes](https://mdpi.com/journal/processes)





Processes

an Open Access Journal
by MDPI

Impact Factor 3.4
CiteScore 5.7



[mdpi.com/journal/
processes](https://mdpi.com/journal/processes)



About the Journal

Message from the Editor-in-Chief

You are invited to contribute either a research article or a comprehensive review for consideration and publication in *Processes*. *Processes* is published in open access format – research articles, reviews, and other content are released on the internet immediately after acceptance. The scientific community and the general public have unlimited, free access to the content. As an open access journal, *Processes* is supported by the authors and their institutes through the payment of article processing charges (APCs) for accepted papers. We would be pleased to welcome you as one of our authors.

Editor-in-Chief

Prof. Dr. Giancarlo Cravotto

Department of Drug Science and Technology, University of Turin, Via P. Giuria 9, 10125 Turin, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, AGRIS, and other databases.

Journal Rank:

CiteScore - Q2 (Chemical Engineering (miscellaneous))